

Title (en)  
SEMICONDUCTOR ELEMENT AND METHOD FOR PRODUCING THE SAME

Title (de)  
HALBLEITERBAUELEMENT UND VERFAHREN ZUR HERSTELLUNG DESSELBEN

Title (fr)  
COMPOSANT À SEMI-CONDUCTEURS ET PROCÉDÉ POUR LE PRODUIRE

Publication  
**EP 2577725 A2 20130410 (DE)**

Application  
**EP 11791422 A 20110530**

Priority  
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Abstract (en)  
[origin: WO2012006991A2] The invention relates to a semiconductor element having at least one semiconductor chip, two contacting layers which are arranged on two faces of the semiconductor and cover at least sections of the faces of the semiconductor chip, and further having a metal body which is associated with a first face of the semiconductor chip at a distance, said metal body being connected to the semiconductor chip in a thermally and electrically conducting manner via finger-type connecting webs that project from the contacting layer associated with the first face. The finger-type connecting webs are interspaced from each other and the finger-type connecting webs are monolithically connected to the contacting layer.

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Citation (search report)  
See references of WO 2012006991A2

Citation (examination)  
DE 102006009021 A1 20060831 - OCTEC INC [JP], et al

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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